

## I) IC Lab Schedule (EMD/OOE 2009)

DATE	LAB	DESCRIPTION
August 31	0	Safety Lecture
September 01	1	Lab tour; Safety discussion; Determining charge carrier type; Determining resistivity.
September 02	2	Wafer clean; Wet oxidation.
September 03	3	Photolithography Level 1; Oxide etch; Strip resist; Wafer clean; Spin on dopant glass.
September 04	4	Diffuse; Etch dopant glass; Demonstrate diode electrical characteristics.
September 07 (Labor Day)	5	Photolithography Level 2; Oxide etch; Strip resist; Wafer clean; Gate oxidation
September 08	6	Photolithography Level 3; Oxide etch; Strip resist; Photolithography Level 4.
September 09	7	Evaporate aluminum; Lift-off; Sinter & Anneal; Solder to glass slide
September 10	9	International Student Orientation
September 11	10	International Student Orientation
September 14	11	Electrical Measurements.
September 15	12	Electrical Measurements.
September 16	13	Electrical Measurements.
September 17		Classes Begin